

IN THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 2, 6, 7 and 10 have been canceled, claims 1 and 5 have been amended and claims 11-16 have been added as follows:

Listing of Claims:

Claim 1 (currently amended): A resin plating method with an added heat-treating process for a resin molding, in which resin plating is performed after a specific portion of the resin molding which portion is apt to undergo peeling of a thin surface resin film of the resin molding is heat-treated at a high temperature.

Claim 2 (canceled)

Claim 3 (original): A resin plating method with an added heat-treating process according to claim 1,

wherein the resin molding is heat-treated at a high temperature so that rubber particles in the resin surface of the resin molding retains a generally circular shape.

Claim 4 (original): A resin plating method with an added heat-treating process according to claim 1,

wherein the resin molding is heat-treated at a high temperature so that rubber particles in the resin surface of the resin molding retain a circular shape of 2:3 or less in terms of a size ratio in longitudinal and transverse directions.

Claim 5 (currently amended): A resin plating method with an added heat-treating process according to ~~any of claims 1 to 4~~ claim 1,

wherein a parting line portion of the resin molding is heat-treated at a high temperature.

Claim 6 (canceled)

Claim 7 (canceled)

Claim 8 (original): A resin plating method with an added heat-treating process according to claim 5,

wherein in the case where the resin molding is formed of ABS resin, the high-temperature heat treatment is performed in a heating temperature range corresponding a surface temperature range of the resin molding of 80° to 150°C.

Claim 9 (original): A resin plating method with an added heat-treating process according to claim 5,

wherein in the case where the resin molding is formed of PC/ABS resin, the high-temperature heat treatment is performed in a heating temperature range corresponding to a surface temperature range of the resin molding of 100° to 200°C.

Claim 10 (canceled)

Claim 11 (new): A resin plating method with an added heat-treating process according to claim 3,

wherein a parting line portion of the resin molding is heat-treated at a high temperature.

Claim 12 (new): A resin plating method with an added heat-treating process according to claim 4,

wherein a parting line portion of the resin molding is heat-treated at a high temperature.

Claim 13 (new): A resin plating method with an added heat-treating process according to claim 3,

wherein in the case where the resin molding is formed of ABS resin, the high-temperature heat treatment is performed in a heating temperature range corresponding a surface temperature range of the resin molding of 80° to 150°C.

Claim 14 (new): A resin plating method with an added heat-treating process according to claim 4,

wherein in the case where the resin molding is formed of ABS resin, the high-temperature heat treatment is performed in a heating temperature range corresponding a surface temperature range of the resin molding of 80° to 150°C.

Claim 15 (new): A resin plating method with an added heat-treating process according to claim 3,

wherein in the case where the resin molding is formed of PC/ABS resin, the high-temperature heat treatment is performed in a heating temperature range corresponding to a surface temperature range of the resin molding of 100° to 200°C.

Claim 16 (new): A resin plating method with an added heat-treating process according to claim 4,

wherein in the case where the resin molding is formed of PC/ABS resin, the high-temperature heat treatment is performed in a heating temperature range corresponding to a surface temperature range of the resin molding of 100° to 200°C.